

#441426-02

In re Patent Application of: : Docket: Y0R919990336US2
Chao-kun Hu et al. : Prior Group Art Unit: 2815
Serial No.: To be Assigned : Prior Examiner: A. Wilson
Filed: Herewith : Date: November 13, 2001
For: REDUCED ELECTROMIGRATION AND STRESSED INDUCED MIGRATION
OF Cu WIRES BY SURFACE COATING

J1002 U.S. PRO
10/054605
11/13/01



INFORMATION DISCLOSURE STATEMENT
PURSUANT TO 37 C.F.R. §1.98(d)

Commissioner for Patents
Washington, D.C. 20231

Sir:

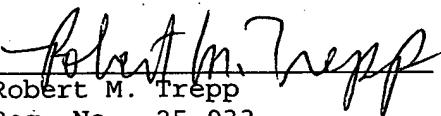
Pursuant to applicants' duty of disclosure under 37 C.F.R. §1.56 and consistent with 37 C.F.R. §§1.97 and 1.98, submitted herewith is a Form PTO-1449 listing references that may be material to the above-captioned application.

The listed references were previously cited by or submitted to the Patent and Trademark Office in prior parent application, U.S. Serial No. 09/361,573, filed July 27, 1999, reliance upon which for an earlier effective filing date is claimed under 35 U.S.C. §120. Accordingly, pursuant to 37 C.F.R. §1.98(d) copies of said references are not enclosed herewith.

This information Disclosure Statement is being submitted concurrently at filing, thus no fee or certification under 37 C.F.R. §1.97 is required.

Respectfully submitted,
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by


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